Vishay High Power Products

FlipKY[®], 1 A Chip Scale Package Schottky Barrier Rectifier



FlipKY[®]

1 A

40 V

PRODUCT SUMMARY

I_{F(AV)}

 V_{R}

SHA

Low thermal resistanceOne-fifth footprint of SMA

FEATURES

· Low leakage

• Super low profile (0.6 mm)

• Ultra low V_F per footprint area

• Available tested on tape and reel

APPLICATIONS

- Reverse polarity protection
- · Current steering
- Freewheeling
- Flyback
- Oring

DESCRIPTION

Vishay's FlipKY[®] product family utilizes wafer level chip scale packaging to deliver Schottky diodes with the lowest V_F to PCB footprint area in industry. The four bump 1.5 x 1.5 mm devices can deliver up to 1 A and occupy only 2.3 mm² of board space. The anode and cathode connections are made through solder bump pads on one side of the silicon enabling designers to strategically place the diodes on the PCB. This design not only minimizes board space but also reduces thermal resistance and inductance, which can improve overall circuit efficiency.

Typical applications include hand-held, portable equipment such as cell phones, MP3 players, bluetooth, GPS, PDAs, and portable hard disk drives where space savings and performance are crucial.

MAJOR RATINGS AND CHARACTERISTICS					
SYMBOL	CHARACTERISTICS	MAX.	UNITS		
V _{RRM}		40	V		
I _{F(AV)}	Rectangular waveform	1	٨		
I _{FSM}		250	A		
V _F	1 Apk, T _J = 125 °C	0.42	V		
TJ		- 55 to 150	°C		

VOLTAGE RATINGS						
PARAMETER	SYMBOL	FCSP1H40LTR	UNITS			
Maximum DC reverse voltage	V _R	40	V			
Maximum working peak reverse voltage	V _{RWM}	40				



1

Vishay High Power Products

FlipKY[®], 1 A Chip Scale Package Schottky Barrier Rectifier

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$ 50 % duty cycle at T_{PCB} = 117 °C, rectangular waveform		1.0		
Maximum peak one cycle non-repetitive surge current at 25 °C	I _{FSM}	5 μs sine or 3 μs rect. pulse	Following any rated load condition and with rated V _{RRM} applied	250	A
		10 ms sine or 6 ms rect. pulse		21	
Non-repetitive avalanche energy	E _{AS}	T _J = 25 °C, I _{AS} = 2.0 A, L = 5.0 mH		10	mJ
Repetitive avalanche current	I _{AR}	Current decaying linearly to zero in 1 μ s Frequency limited by T _J maximum V _A = 1.5 x V _R typical		2.0	А

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS		TYP.	MAX.	UNITS
Maximum forward voltage drop See fig. 1	V _{FM} ⁽¹⁾	1 A	T.I = 25 °C	0.48	0.52	v
		2 A		0.54	0.59	
		1 A	T 105 %C	0.38	0.42	
		2 A	Τ _J = 125 °C	0.48	0.52	
	I _{RM} ⁽¹⁾	T _J = 25 °C	V _R = Rated V _R	3	15	μΑ - μΑ - mA
			V _R = 20 V	0.5	1	
			V _R = 10 V	0.2	0.5	
Maximum reverse leakage current			V _R = 5 V	0.15	0.3	
See fig. 2		T _J = 125 °C	V _R = Rated V _R	2.5	4	
			V _R = 20 V	0.9	2	
			V _R = 10 V	0.6	1.5	
			V _R = 5 V	0.5	1	
Maximum junction capacitance	CT	V_R = 5 V_{DC} (test signal range 100 kHz to 1 MHz) 25 °C		-	160	pF
Maximum voltage rate of charge dV/dt Rated V _R			-	10 000	V/µs	

Note

 $^{(1)}\,$ Pulse width < 300 $\mu s,$ duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Maximum junction and storage temperature range	T _J ⁽¹⁾ , T _{Stg}		- 55 to 150	°C	
Typical thermal resistance, junction to PCB	R _{thJL} ⁽²⁾	DC operation	40	°C/W	
Maximum thermal resistance, junction to ambient	R _{thJA}		62	0/11	

Notes

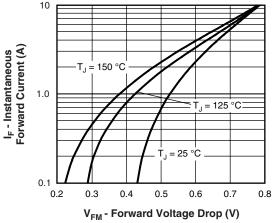
(1)

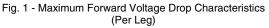
 $\frac{dP_{tot}}{dT_J} < \frac{1}{R_{thJA}}$ thermal runaway condition for a diode on its own heatsink

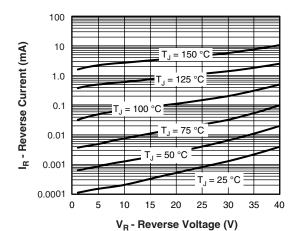
(2) Mounted 1" square PCB

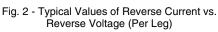


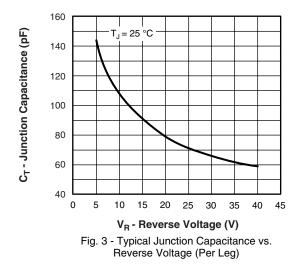
FlipKY[®], 1 A Vishay High Power Products Chip Scale Package Schottky Barrier Rectifier

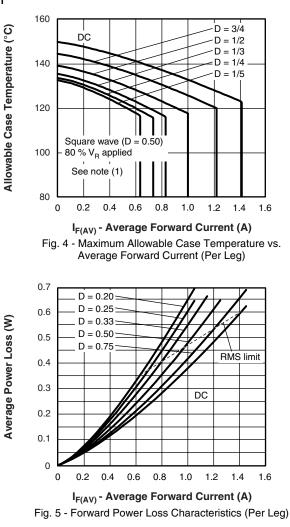


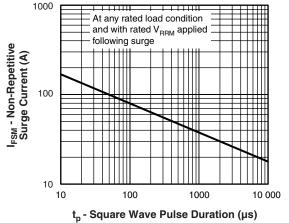














Note

⁽¹⁾ Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$;

Pd = Forward power loss = $I_{F(AV)}$ x V_{FM} at $(I_{F(AV)}/D)$ (see fig. 6); Pd_{REV} = Inverse power loss = V_{R1} x I_R (1 - D); I_R at 80 % V_R applied



Vishay High Power Products

FlipKY[®], 1 A Chip Scale Package Schottky Barrier Rectifier

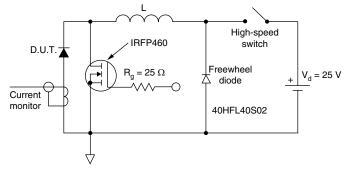


Fig. 7 - Unclamped Inductive Test Circuit

LINKS TO RELATED DOCUMENTS				
Dimensions	http://www.vishay.com/doc?95282			
Part marking information	http://www.vishay.com/doc?95281			
Packaging information	http://www.vishay.com/doc?95062			



Vishay

Disclaimer

All product specifications and data are subject to change without notice.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained herein or in any other disclosure relating to any product.

Vishay disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications unless otherwise expressly indicated. Customers using or selling Vishay products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Vishay for any damages arising or resulting from such use or sale. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

Product names and markings noted herein may be trademarks of their respective owners.